10/19/2015 503528224

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HUAPU PAN	04/29/2015
ZONGRONG LIU	05/01/2015
HONGZHEN WEI	10/13/2015
HONGMIN CHEN	06/16/2015

RECEIVING PARTY DATA

Name:	Futurewei Technologies, Inc.	
Street Address:	5340 Legacy Drive	
Internal Address:	Suite 175	
City:	Plano	
State/Country:	TEXAS	
Postal Code:	75024	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14680917

CORRESPONDENCE DATA

Fax Number: (972)731-2289

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 972-731-2288

Email: dallaspatents@dfw.conleyrose.com

Correspondent Name: GRANT RODOLPH

Address Line 1: 5601 GRANITE PARKWAY, SUITE 500

PLANO, TEXAS 75024-6616 Address Line 4:

ATTORNEY DOCKET NUMBER:	4194-93601 (91014936US02)	
NAME OF SUBMITTER:	WILLIAM H. DIETRICH	
SIGNATURE:	/William H. Dietrich/	
DATE SIGNED:	10/19/2015	

Total Attachments: 5

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WHEREAS, I/We, the undersigned inventor(s) (or one of the undersigned joint inventors), of residence as listed below, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Futurewei Technologies, Inc. ("Assignee"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024 is desirous of acquiring my/our entire right, title and interest in the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I/we will assign, and hereby assign and transfer to the Assignee and the Assignee's legal representatives, successors and assigns the full and exclusive right, title and interest in and to the invention in the United States and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisional, reissues, reexaminations, National Phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and I/we do hereby authorize and request the Commissioner for Patents to issue U.S. patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the Assignee agreeably with the terms of this assignment document.

I also hereby agree to sell and to assign, and sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to Assignee, or its successors, assigns, and legal representative, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid such Futurewei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

Futurewei Technologies, Inc. Patent Reference No. 91014936US02 Conley Rose File: 4194-93601

Page 1 of 2

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	Edge Coupling Device Fabrication	
	Appl. No. 14/680,917	Filing Date: April 7, 2015
Signature of Inventor	Hrapu Pan	
Inventor Name	Huapu Pan	Hongzhen Wei
Date	04/29/2015	
Residence (City/State)	San Jose, California	Pleasanton, California
Signature of Inventor		
Inventor Name	Zongrong Liu	Hongmin Chen
Date		
Residence (City/State)	Pleasanton, California	Davis, California

Futurewei Technologies, Inc. Patent Reference No. 91014936US02 Conley Rose File: 4194-93601

Page 2 of 2

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Title of Invention	Edge Coupling De	Edge Coupling Device Fabrication	
	Appl. No. 14/680,917	Filing Date: April 7, 2015	
Signature of Inventor			
Inventor Name	Huapu Pan	Hongzhen Wei	
Date			
Residence (City/State)	San Jose, California	Pleasanton, California	
Signature of Inventor	Jonesiand (=		
Inventor Name	Zongrong Liu	Hongmin Chen	
Date	of/01/2015		
Residence (City/State)	Pleasanton, California	Davis, California	

Futurewei Technologies, Inc. Patent Reference No. 91014936US02 Conley Rose File: 4194-93601

Page 2 of 2

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Fitle of Invention	Edge Coupl	ing Device Fabrication
	Appl. No. 14/680,917	Filing Date: April 7, 2015
Signature of Inventor		Hongchennini
Inventor Name	Huapu Pan	Hongzhen Wei
Date		10-13-2015.
Residence (City/State)	San Jose, California	Pleasanton, California
Signature of Inventor		
Inventor Name	Zongrong Liu	Hongmin Chen
Date		
Residence (City/State)	Pleasanton, California	Davis, California

Futurewei Technologies, Inc. Patent Reference No. 91014936US02 Conley Rose File: 4194-93601 Page 2 of 2

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Title of Invention	Edge Coupling	Edge Coupling Device Fabrication	
	Appl. No. 14/680,917	Filing Date: April 7, 2015	
Signature of Inventor			
Inventor Name	Huapu Pan	Hongzhen Wei	
Date			
Residence (City/State)	San Jose, California	Pleasanton, California	
Signature of Inventor			
Inventor Name	Zongrong Liu	Hongmin Chen	
Date	06/16/2015	Jerse	
Residence (City/State)	Pleasanton, California	Davis, California	

Futurewei Technologies, Inc. Patent Reference No. 91014936US02 Conley Rose File: 4194-93601

RECORDED: 10/19/2015

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